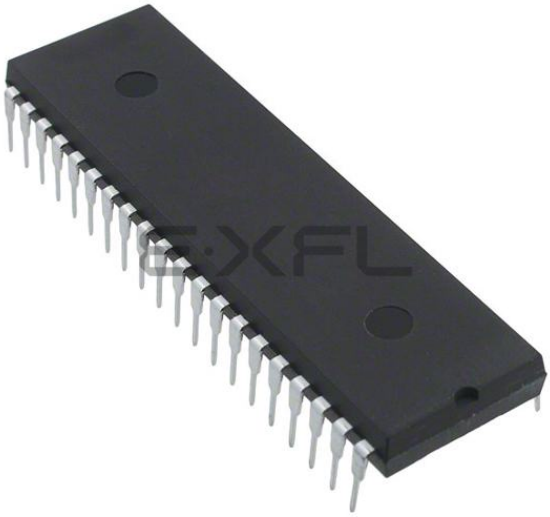

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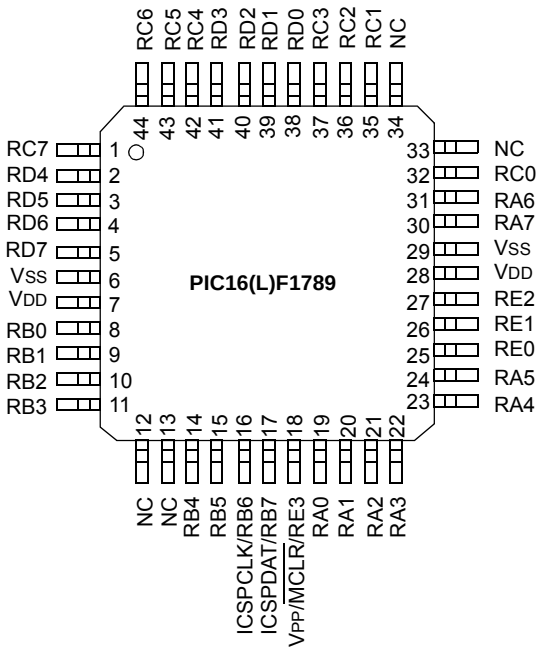
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PSMC, PWM, WDT
Number of I/O	35
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x12b; D/A 1x8b, 3x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1789-i-p

Pin Diagram – 44-Pin TQFP



Note: See Table 2 for the location of all peripheral functions.

TABLE 1-2: PIC16(L)F1788 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/C1IN0-/C2IN0-/ C3IN0-/C4IN0-/$\overline{SS}$(1)	RA0	TTL/ST	CMOS	General purpose I/O.
	AN0	AN	—	ADC Channel 0 input.
	C1IN0-	AN	—	Comparator C1 negative input.
	C2IN0-	AN	—	Comparator C2 negative input.
	C3IN0-	AN	—	Comparator C3 negative input.
	C4IN0-	AN	—	Comparator C4 negative input.
	$\overline{SS}$	ST	—	Slave Select input.
RA1/AN1/C1IN1-/C2IN1-/ C3IN1-/C4IN1-/OPA1OUT	RA1	TTL/ST	CMOS	General purpose I/O.
	AN1	AN	—	ADC Channel 1 input.
	C1IN1-	AN	—	Comparator C1 negative input.
	C2IN1-	AN	—	Comparator C2 negative input.
	C3IN1-	AN	—	Comparator C3 negative input.
	C4IN1-	AN	—	Comparator C4 negative input.
	OPA1OUT	—	AN	Operational Amplifier 1 output.
RA2/AN2/C1IN0+/C2IN0+/ C3IN0+/C4IN0+/DAC1OUT1/ VREF-/DAC1VREF-	RA2	TTL/ST	CMOS	General purpose I/O.
	AN2	AN	—	ADC Channel 2 input.
	C1IN0+	AN	—	Comparator C1 positive input.
	C2IN0+	AN	—	Comparator C2 positive input.
	C3IN0+	AN	—	Comparator C3 positive input.
	C4IN0+	AN	—	Comparator C4 positive input.
	DAC1OUT1	—	AN	Digital-to-Analog Converter output.
	VREF-	AN	—	ADC Negative Voltage Reference input.
	DAC1VREF-	AN	—	Digital-to-Analog Converter negative reference.
RA3/AN3/VREF+/C1IN1+/ DAC1VREF+/DAC2VREF+/ DAC3VREF+/DAC4VREF+	RA3	TTL/ST	CMOS	General purpose I/O.
	AN3	AN	—	ADC Channel 3 input.
	VREF+	AN	—	ADC Voltage Reference input.
	C1IN1+	AN	—	Comparator C1 positive input.
	DAC1VREF+	AN	—	Digital-to-Analog Converter positive reference.
	DAC2VREF+	AN	—	Digital-to-Analog Converter positive reference.
	DAC3VREF+	AN	—	Digital-to-Analog Converter positive reference.
	DAC4VREF+	AN	—	Digital-to-Analog Converter positive reference.
RA4/C1OUT/OPA1IN+/T0CKI/ DAC4OUT1	RA4	TTL/ST	CMOS	General purpose I/O.
	C1OUT	—	CMOS	Comparator C1 output.
	OPA1IN+	AN	—	Operational Amplifier 1 non-inverting input.
	T0CKI	ST	—	Timer0 clock input.
	DAC4OUT1	—	AN	Digital-to-Analog Converter output.
RA5/AN4/C2OUT/OPA1IN-/ $\overline{SS}$(1)/DAC2OUT1	RA5	TTL/ST	CMOS	General purpose I/O.
	AN4	AN	—	ADC Channel 4 input.
	C2OUT	—	CMOS	Comparator C2 output.
	OPA1IN-	AN	—	Operational Amplifier 1 inverting input.
	$\overline{SS}$	ST	—	Slave Select input.
	DAC2OUT1	—	AN	Digital-to-Analog Converter output.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open-Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2C
HV = High Voltage XTAL = Crystal levels

Note 1: Pin functions can be assigned to one of two locations via software. See **Register 13-1**.
2: All pins have interrupt-on-change functionality.

3.3.4 DEVICE MEMORY MAPS

The memory maps for Bank 0 through Bank 31 are shown in the tables in this section.

TABLE 3-3: PIC16(L)F1788 MEMORY MAP (BANKS 0-7)

BANK 0		BANK 1		BANK 2		BANK 3		BANK 4		BANK 5		BANK 6		BANK 7	
000h	Core Registers (Table 3-2)	080h	Core Registers (Table 3-2)	100h	Core Registers (Table 3-2)	180h	Core Registers (Table 3-2)	200h	Core Registers (Table 3-2)	280h	Core Registers (Table 3-2)	300h	Core Registers (Table 3-2)	380h	Core Registers (Table 3-2)
00Bh		08Bh		10Bh		18Bh		20Bh		28Bh		30Bh		38Bh	
00Ch	PORTA	08Ch	TRISA	10Ch	LATA	18Ch	ANSELA	20Ch	WPUA	28Ch	ODCONA	30Ch	SLRCONA	38Ch	INLVLA
00Dh	PORTB	08Dh	TRISB	10Dh	LATB	18Dh	ANSELB	20Dh	WPUB	28Dh	ODCONB	30Dh	SLRCONB	38Dh	INLVLB
00Eh	PORTC	08Eh	TRISC	10Eh	LATC	18Eh	ANSELC	20Eh	WPUC	28Eh	ODCONC	30Eh	SLRCONC	38Eh	INLVLC
00Fh	—	08Fh	—	10Fh	—	18Fh	—	20Fh	—	28Fh	—	30Fh	—	38Fh	—
010h	PORTE	090h	TRISE	110h	—	190h	—	210h	WPUE	290h	—	310h	—	390h	INLVLE
011h	PIR1	091h	PIE1	111h	CM1CON0	191h	EEADRL	211h	SSP1BUF	291h	CCPR1L	311h	CCPR3L	391h	IOCAP
012h	PIR2	092h	PIE2	112h	CM1CON1	192h	EEADRH	212h	SSP1ADD	292h	CCPR1H	312h	CCPR3H	392h	IOCAN
013h	PIR3	093h	PIE3	113h	CM2CON0	193h	EEDATL	213h	SSP1MSK	293h	CCP1CON	313h	CCP3CON	393h	IOCAF
014h	PIR4	094h	PIE4	114h	CM2CON1	194h	EEDATH	214h	SSP1STAT	294h	—	314h	—	394h	IOCBP
015h	TMR0	095h	OPTION_REG	115h	CMOUT	195h	EECON1	215h	SSP1CON1	295h	—	315h	—	395h	IOCBN
016h	TMR1L	096h	PCON	116h	BORCON	196h	EECON2	216h	SSP1CON2	296h	—	316h	—	396h	IOCBF
017h	TMR1H	097h	WDTCON	117h	FVRCON	197h	VREGCON(1)	217h	SSP1CON3	297h	—	317h	—	397h	IOCCP
018h	T1CON	098h	OSCTUNE	118h	DAC1CON0	198h	—	218h	—	298h	CCPR2L	318h	—	398h	IOCCN
019h	T1GCON	099h	OSCCON	119h	DAC1CON1	199h	RC1REG	219h	—	299h	CCPR2H	319h	—	399h	IOCCF
01Ah	TMR2	09Ah	OSCSTAT	11Ah	CM4CON0	19Ah	TX1REG	21Ah	—	29Ah	CCP2CON	31Ah	—	39Ah	—
01Bh	PR2	09Bh	ADRESL	11Bh	CM4CON1	19Bh	SP1BRGL	21Bh	—	29Bh	—	31Bh	—	39Bh	—
01Ch	T2CON	09Ch	ADRESH	11Ch	APFCON2	19Ch	SP1BRGH	21Ch	—	29Ch	—	31Ch	—	39Ch	—
01Dh	—	09Dh	ADCON0	11Dh	APFCON1	19Dh	RC1STA	21Dh	—	29Dh	—	31Dh	—	39Dh	—
01Eh	—	09Eh	ADCON1	11Eh	CM3CON0	19Eh	TX1STA	21Eh	—	29Eh	—	31Eh	—	39Eh	—
01Fh	—	09Fh	ADCON2	11Fh	CM3CON1	19Fh	BAUD1CON	21Fh	—	29Fh	—	31Fh	—	39Fh	—
020h	General Purpose Register 80 Bytes	0A0h	General Purpose Register 80 Bytes	120h	General Purpose Register 80 Bytes	1A0h	General Purpose Register 80 Bytes	220h	General Purpose Register 80 Bytes	2A0h	General Purpose Register 80 Bytes	320h	General Purpose Register 80 Bytes	3A0h	General Purpose Register 80 Bytes
06Fh		0EFh		16Fh		1EFh		26Fh		2EFh		36Fh		3EFh	
070h	Common RAM 70h – 7Fh	0F0h	Accesses 70h – 7Fh	170h	Accesses 70h – 7Fh	1F0h	Accesses 70h – 7Fh	270h	Accesses 70h – 7Fh	2F0h	Accesses 70h – 7Fh	370h	Accesses 70h – 7Fh	3F0h	Accesses 70h – 7Fh
07Fh		0FFh		17Fh		1FFh		27Fh		2FFh		37Fh		3FFh	

Legend: = Unimplemented data memory locations, read as '0'.

Note 1: PIC16F1788 only.

3.5 Stack

All devices have a 16-level x 15-bit wide hardware stack (refer to Figure 3-1). The stack space is not part of either program or data space. The PC is PUSHed onto the stack when CALL or CALLW instructions are executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer if the STVREN bit is programmed to '0' (Configuration Words). This means that after the stack has been PUSHed sixteen times, the seventeenth PUSH overwrites the value that was stored from the first PUSH. The eighteenth PUSH overwrites the second PUSH (and so on). The STKOVF and STKUNF flag bits will be set on an Overflow/Underflow, regardless of whether the Reset is enabled.

Note:	There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, CALLW, RETURN, RETLW and RETFIE instructions or the vectoring to an interrupt address.

3.5.1 ACCESSING THE STACK

The stack is available through the TOSH, TOSL and STKPTR registers. STKPTR is the current value of the Stack Pointer. TOSH:TOSL register pair points to the TOP of the stack. Both registers are read/writable. TOS is split into TOSH and TOSL due to the 15-bit size of the PC. To access the stack, adjust the value of STKPTR, which will position TOSH:TOSL, then read/write to TOSH:TOSL. STKPTR is five bits to allow detection of overflow and underflow.

Note:	Care should be taken when modifying the STKPTR while interrupts are enabled.

During normal program operation, CALL, CALLW and interrupts will increment STKPTR while RETLW, RETURN, and RETFIE will decrement STKPTR. At any time, STKPTR can be inspected to see how much stack is left. The STKPTR always points at the currently used place on the stack. Therefore, a CALL or CALLW will increment the STKPTR and then write the PC, and a return will unload the PC and then decrement the STKPTR.

Reference Figure 3-4 through Figure 3-7 for examples of accessing the stack.

FIGURE 3-4: ACCESSING THE STACK EXAMPLE 1

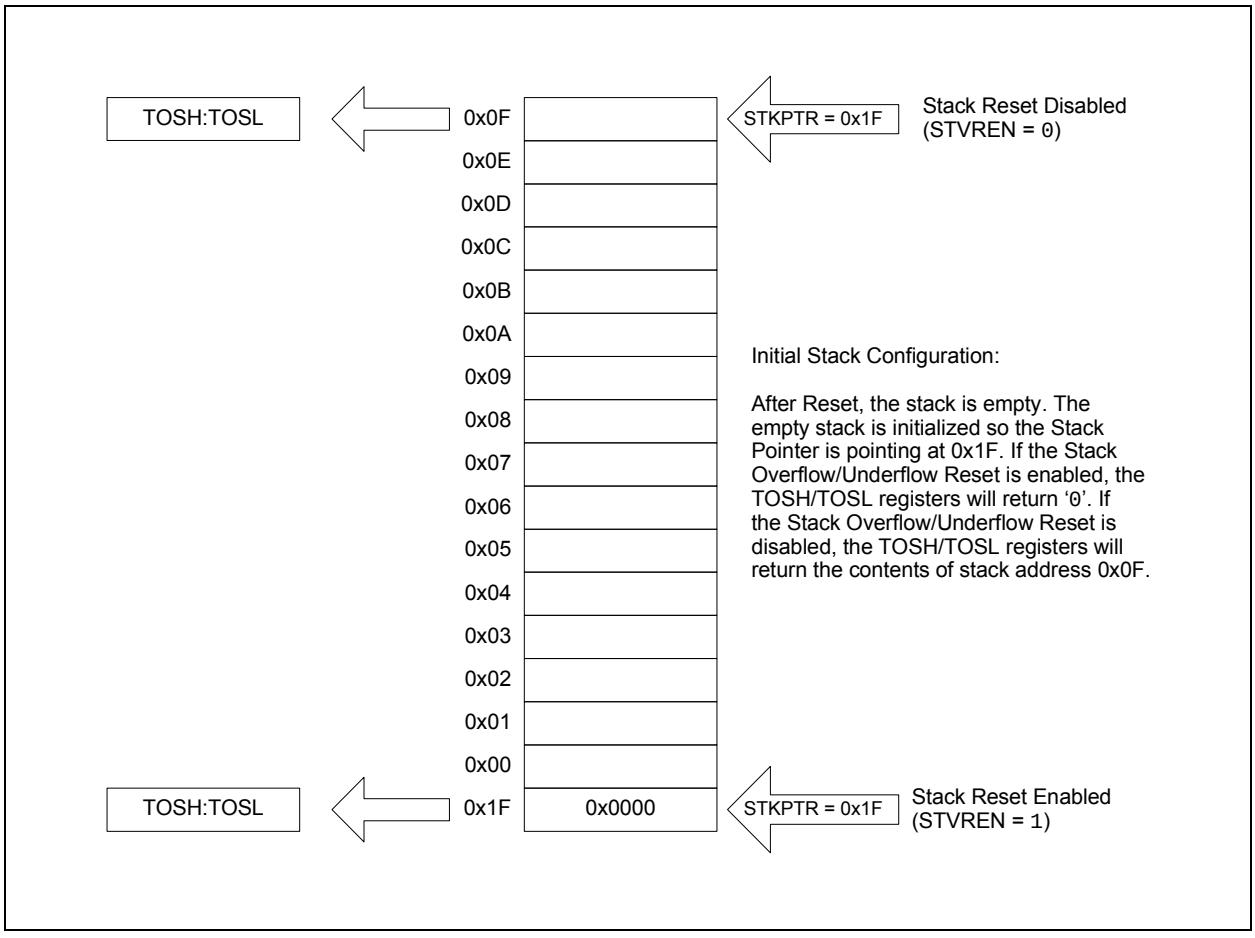
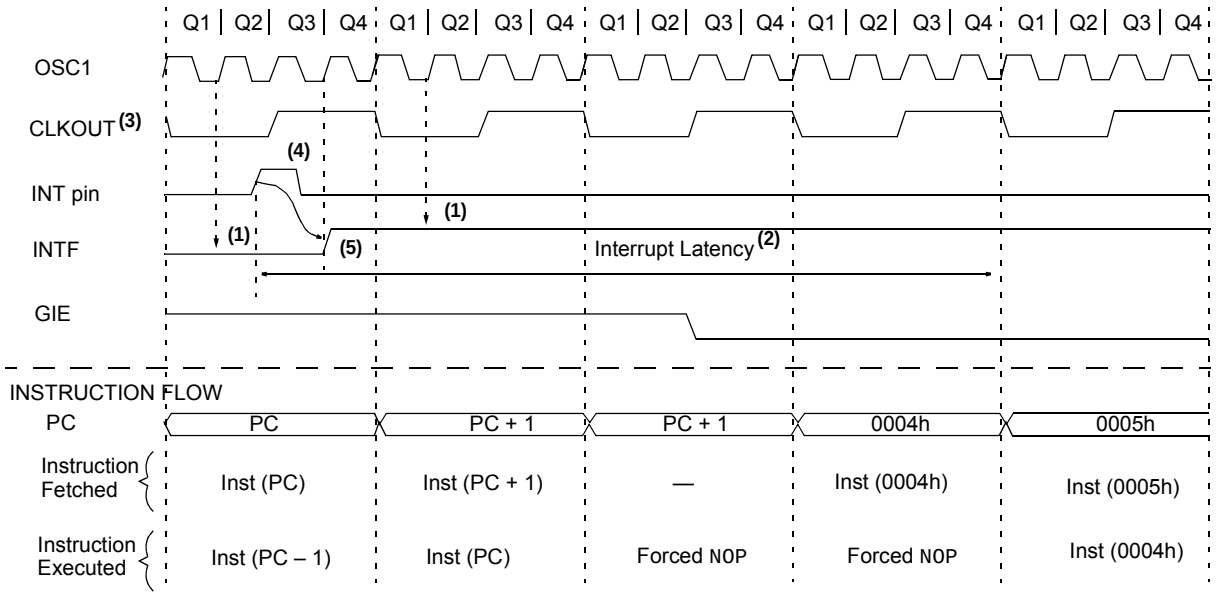


FIGURE 8-3: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-5 TCY. Synchronous latency = 3-4 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT not available in all oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 31.0 "Electrical Specifications"**".

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

9.2 Low-Power Sleep Mode

"F" devices contain an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode. "F" devices allow the user to optimize the operating current in Sleep, depending on the application requirements.

A Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. With this bit set, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

9.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

9.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The LDO will remain in the normal power mode when those peripherals are enabled. The Low-Power Sleep mode is intended for use with these peripherals:

- Brown-Out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source)

Note:	"LF" devices do not have a configurable Low-Power Sleep mode. "LF" devices are an unregulated device and are always in the lowest power state when in Sleep, with no wake-up time penalty. These devices have a lower maximum V_{DD} and I/O voltage than "F" devices. See **Section 31.0 "Electrical Specifications"** for more information.

EXAMPLE 12-6: WRITING TO FLASH PROGRAM MEMORY

```
; This write routine assumes the following:
; 1. The 16 bytes of data are loaded, starting at the address in DATA_ADDR
; 2. Each word of data to be written is made up of two adjacent bytes in DATA_ADDR,
;    stored in little endian format
; 3. A valid starting address (the least significant bits = 0000) is loaded in ADDRH:ADDRL
; 4. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)
;
        BCF         INTCON,GIE     ; Disable ints so required sequences will execute properly
        BANKSEL     EEADRH         ; Bank 3
        MOVF        ADDRH,W        ; Load initial address
        MOVWF       EEADRH         ;
        MOVF        ADDRL,W        ;
        MOVWF       EEADRL         ;
        MOVLW       LOW DATA_ADDR  ; Load initial data address
        MOVWF       FSR0L          ;
        MOVLW       HIGH DATA_ADDR ; Load initial data address
        MOVWF       FSR0H          ;
        BSF         EECON1,EEPGD   ; Point to program memory
        BCF         EECON1,CFGS    ; Not configuration space
        BSF         EECON1,WREN    ; Enable writes
        BSF         EECON1,LWLO    ; Only Load Write Latches
LOOP
        MOVIW       FSR0++         ; Load first data byte into lower
        MOVWF       EEDATL         ;
        MOVIW       FSR0++         ; Load second data byte into upper
        MOVWF       EEDATH         ;

        MOVF        EEADRL,W       ; Check if lower bits of address are '000'
        XORLW       0x0F           ; Check if we're on the last of 16 addresses
        ANDLW       0x0F           ;
        BTFSC       STATUS,Z       ; Exit if last of 16 words,
        GOTO        START_WRITE    ;

  Required Sequence
        MOVLW       55h            ; Start of required write sequence:
        MOVWF       EECON2         ; Write 55h
        MOVLW       0AAh           ;
        MOVWF       EECON2         ; Write AAh
        BSF         EECON1,WR      ; Set WR bit to begin write
        NOP                        ; Any instructions here are ignored as processor
                                   ; halts to begin write sequence
        NOP                        ; Processor will stop here and wait for write to complete.

                                   ; After write processor continues with 3rd instruction.

        INCF        EEADRL,F       ; Still loading latches Increment address
        GOTO        LOOP           ; Write next latches

START_WRITE
        BCF         EECON1,LWLO    ; No more loading latches - Actually start Flash program
                                   ; memory write

  Required Sequence
        MOVLW       55h            ; Start of required write sequence:
        MOVWF       EECON2         ; Write 55h
        MOVLW       0AAh           ;
        MOVWF       EECON2         ; Write AAh
        BSF         EECON1,WR      ; Set WR bit to begin write
        NOP                        ; Any instructions here are ignored as processor
                                   ; halts to begin write sequence
        NOP                        ; Processor will stop here and wait for write complete.

                                   ; after write processor continues with 3rd instruction
        BCF         EECON1,WREN    ; Disable writes
        BSF         INTCON,GIE     ; Enable interrupts
```

REGISTER 13-25: INLVLC: PORTC INPUT LEVEL CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
INLVLC7	INLVLC6	INLVLC5	INLVLC4	INLVLC3	INLVLC2	INLVLC1	INLVLC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **INLVLC<7:0>:** PORTC Input Level Select bits
For RC<7:0> pins, respectively
1 = ST input used for PORT reads and interrupt-on-change
0 = TTL input used for PORT reads and interrupt-on-change

TABLE 13-8: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
LATC	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	147
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	147
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	147
WPUC	WPUC7	WPUC6	WPUC5	WPUC4	WPUC3	WPUC2	WPUC1	WPUC0	148
INLVLC	INLVLC7	INLVLC6	INLVLC5	INLVLC4	INLVLC3	INLVLC2	INLVLC1	INLVLC0	149
LATC	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	147
ODCONC	ODC7	ODC6	ODC5	ODC4	ODC3	ODC2	ODC1	ODC0	148
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	147
SLRCONC	SLRC7	SLRC6	SLRC5	SLRC4	SLRC3	SLRC2	SLRC1	SLRC0	148

Legend: x = unknown, u = unchanged, - = unimplemented locations read as ‘0’. Shaded cells are not used by PORTC.

17.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
  - Single-ended
  - Differential
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

17.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 13.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

17.1.2 CHANNEL SELECTION

There are up to 18 channel selections available:

- AN<13:8, 4:0> pins (PIC16(L)F1788 only)
- AN<21, 13:0> pins (PIC16(L)F1789 only)
- Temperature Indicator
- DAC_output
- FVR (Fixed Voltage Reference) Output

Refer to **Section 15.0 "Fixed Voltage Reference (FVR)"** and **Section 16.0 "Temperature Indicator Module"** for more information on these channel selections.

When converting differential signals, the negative input for the channel is selected with the CHSN<3:0> bits of the ADCON2 register. Any positive input can be paired with any negative input to determine the differential channel.

The CHS<4:0> bits of the ADCON0 register determine which positive channel is selected.

When CHSN<3:0> = 1111 then the ADC is effectively a single ended ADC converter.

When changing channels, a delay is required before starting the next conversion.

17.1.3 ADC VOLTAGE REFERENCE

The ADPREF bits of the ADCON1 register provide control of the positive voltage reference. The positive voltage reference can be:

- V_{REF+}
- V_{DD}
- FVR Buffer1

The ADNREF bits of the ADCON1 register provide control of the negative voltage reference. The negative voltage reference can be:

- V_{REF-} pin
- V_{SS}

See **Section 15.0 "Fixed Voltage Reference (FVR)"** for more details on the Fixed Voltage Reference.

17.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- $F_{OSC}/2$
- $F_{OSC}/4$
- $F_{OSC}/8$
- $F_{OSC}/16$
- $F_{OSC}/32$
- $F_{OSC}/64$
- F_{RC} (dedicated internal F_{RC} oscillator)

The time to complete one bit conversion is defined as T_{AD}. One full 12-bit conversion requires 15 T_{AD} periods as shown in Figure 17-2.

For correct conversion, the appropriate T_{AD} specification must be met. Refer to the ADC conversion requirements in **Section 31.0 "Electrical Specifications"** for more information. Table 17-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the F_{RC}, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

18.4 Register Definitions: Op Amp Control

REGISTER 18-1: OPAxCON: OPERATIONAL AMPLIFIERS (OPAx) CONTROL REGISTERS

R/W-0/0	R/W-0/0	U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
OPAxEN	OPAxSP	—	—	—	OPAxCH<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **OPAxEN:** Op Amp Enable bit
1 = Op amp is enabled
0 = Op amp is disabled and consumes no active power

bit 6 **OPAxSP:** Op Amp Speed/Power Select bit
1 = Comparator operates in high GBWP mode
0 = Reserved. Do not use.

bit 5-3 **Unimplemented:** Read as '0'

bit 2-0 **OPAxCH<2:0>:** Non-inverting Channel Selection bits
111 = Non-inverting input connects to DAC4_output
110 = Non-inverting input connects to DAC3_output
101 = Non-inverting input connects to DAC2_output
100 = Non-inverting input connects to DAC1_output
011 = Non-inverting input connects to FVR Buffer 2 output
010 = Reserved - do not use
001 = Reserved - do not use
000 = Non-inverting input connects to OPAxIN+ pin

TABLE 18-1: SUMMARY OF REGISTERS ASSOCIATED WITH OP AMPS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	ANSA7	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	137
ANSELB	—	ANSB6	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	143
DAC1CON0	DAC1EN	—	DAC1OE1	DAC1OE2	DAC1PSS<1:0>		—	DAC1NSS	192
DAC1CON1	DAC1R<7:0>								192
OPA1CON	OPA1EN	OPA1SP	—	—	—	—	OPA1PCH<1:0>		187
OPA2CON	OPA2EN	OPA2SP	—	—	—	—	OPA2PCH<1:0>		187
OPA3CON(1)	OPA3EN	OPA3SP	—	—	—	—	OPA3PCH<1:0>		187
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	136
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	142
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	147

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by op amps.
Note 1: PIC16(L)F1789 only

20.0 5-BIT DIGITAL-TO-ANALOG CONVERTER (DAC2/3/4) MODULES

The Digital-to-Analog Converter supplies a variable voltage reference, ratiometric with the input source, with 32 selectable output levels.

The input of the DAC can be connected to:

- External VREF+ pin
- VDD supply voltage

The output of the DAC can be configured to supply a reference voltage to the following:

- Comparator positive input
- ADC input channel
- DACxOUT1 pin
- DACxOUT2 pin

The Digital-to-Analog Converter (DACx) can be enabled by setting the DACxEN bit of the DACxCON0 register.

Note:	Register names, I/O pins, and bit names may use the generic designator 'x' to indicate the use of a numeral to distinguish a particular module, when required. The 'x' designator in DACx applies only to DAC2, DAC3, and DAC4.

20.1 Output Voltage Selection

The DAC has 32 voltage level ranges. The 32 levels are set with the DACxR<4:0> bits of the DACxCON1 register.

The DAC output voltage is determined by the following equations:

EQUATION 20-1: DAC OUTPUT VOLTAGE

IF DACxEN = 1

$$V_{OUT} = \left((V_{SOURCE+} - V_{SOURCE-}) \times \frac{DACxR[4:0]}{2^5} \right) + V_{SOURCE-}$$

IF DACxEN = 0 and DACxLPS = 1 and DACxR[4:0] = 11111

$$V_{OUT} = V_{SOURCE+}$$

IF DACxEN = 0 and DACxLPS = 0 and DACxR[4:0] = 00000

$$V_{OUT} = V_{SOURCE-}$$

$V_{SOURCE+} = V_{DD}$, V_{REF}, or FVR BUFFER 2

$V_{SOURCE-} = V_{SS}$

20.2 Ratiometric Output Level

The DAC output value is derived using a resistor ladder with each end of the ladder tied to a positive and negative voltage reference input source. If the voltage of either input source fluctuates, a similar fluctuation will result in the DAC output value.

The value of the individual resistors within the ladder can be found in **Section 31.0 "Electrical Specifications"**.

20.3 DAC Voltage Reference Output

The DAC voltage can be output to the DACxOUT1 and DACxOUT2 pins by setting the respective DACxOE1 and DACxOE2 pins of the DACxCON0 register. Selecting the DAC reference voltage for output on either DACxOUTx pin automatically overrides the digital output buffer and digital input threshold detector functions of that pin. Reading the DACxOUTx pin when it has been configured for DAC reference voltage output will always return a '0'.

Due to the limited current drive capability, a buffer must be used on the DAC voltage reference output for external connections to either DACxOUTx pin. Figure 20-2 shows an example buffering technique.

21.10 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 21-4. Since the analog input pins share their connection with a digital input, they have reverse biased ESD protection diodes to VDD and VSS. The analog input, therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur.

A maximum source impedance of 10 kΩ is recommended for the analog sources. Also, any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current to minimize inaccuracies introduced.

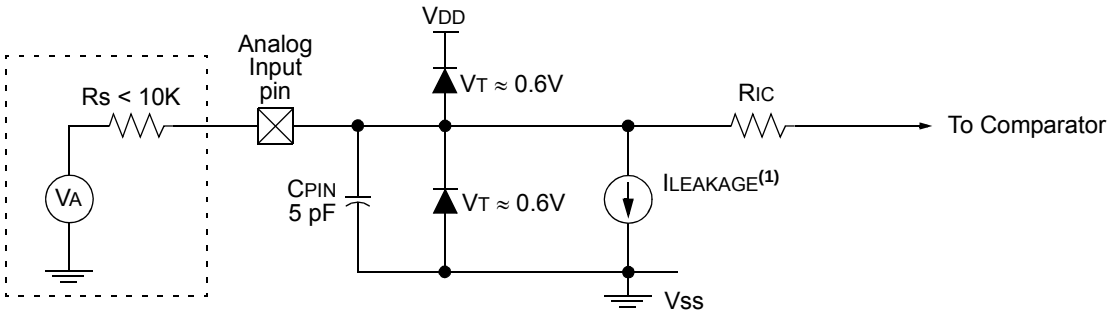
Note 1: When reading a PORT register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert as an analog input, according to the input specification.

2: Analog levels on any pin defined as a digital input, may cause the input buffer to consume more current than is specified.

21.10.1 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function register APFCON. To determine which pins can be moved and what their default locations are upon a Reset, see **Section 13.1 "Alternate Pin Function"** for more information.

FIGURE 21-4: ANALOG INPUT MODEL



Legend: CPIN = Input Capacitance
ILEAKAGE = Leakage Current at the pin due to various junctions
RIC = Interconnect Resistance
RS = Source Impedance
VA = Analog Voltage
VT = Threshold Voltage

Note 1: See **Section 31.0 "Electrical Specifications"**

26.5.3 COMPLEMENTARY PWM STEERING

In Complementary PWM Steering mode, the primary PWM signal (non-complementary) and complementary signal can be steered according to their respective type.

Primary PWM signal can be steered to any of the following outputs:

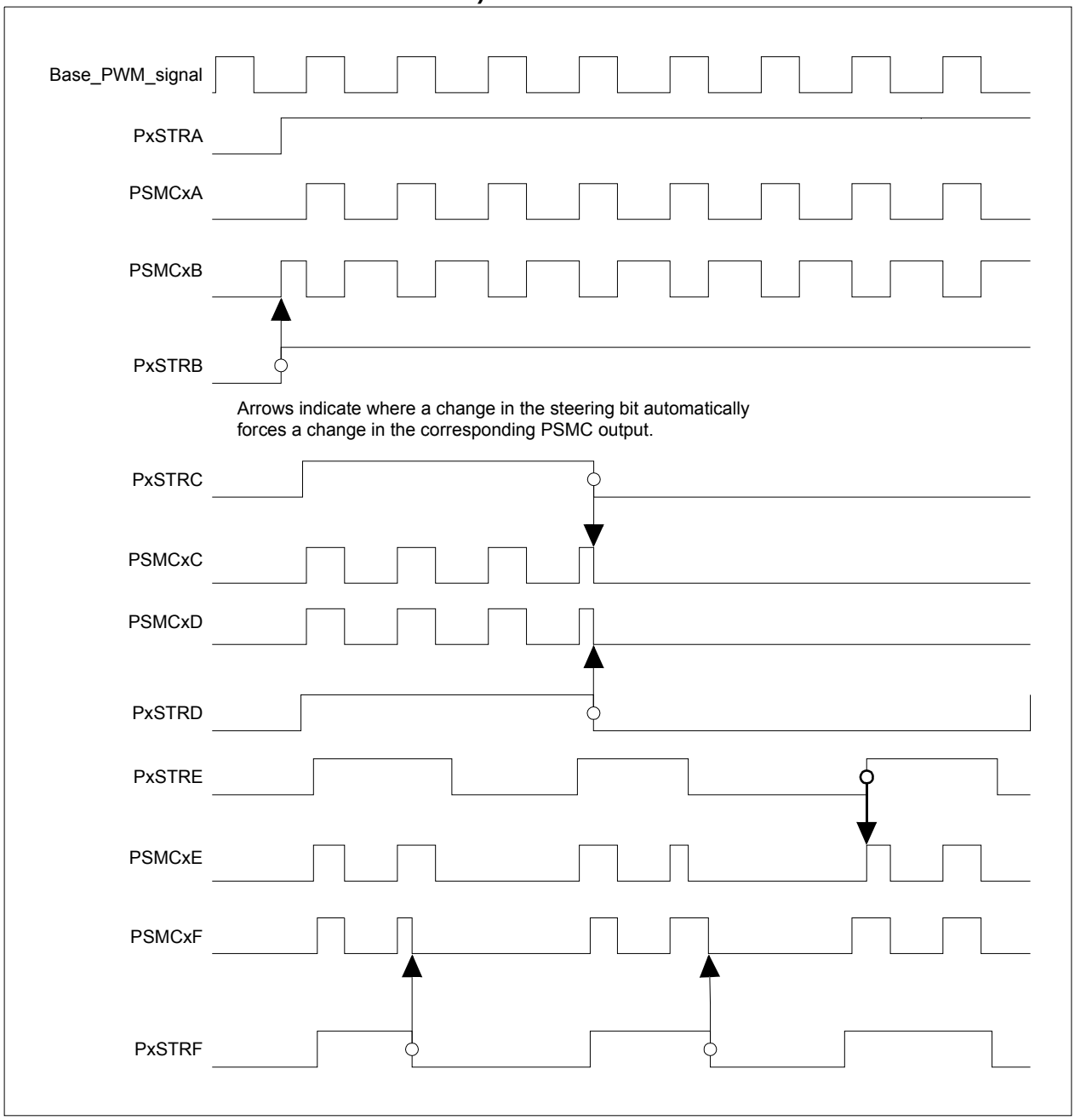
- PSMCxA
- PSMCxC
- PSMCxE

The complementary PWM signal can be steered to any of the following outputs:

- PSMCxB
- PSMCxD
- PSMCxE

Examples of unsynchronized complementary steering are shown in Figure 26-17.

FIGURE 26-17: COMPLEMENTARY PWM STEERING WAVEFORM (NO SYNCHRONIZATION, ZERO DEAD-BAND TIME)



26.8 PSMC Synchronization

It is possible to synchronize the periods of two or more PSMC modules together, provided that all modules are on the same device.

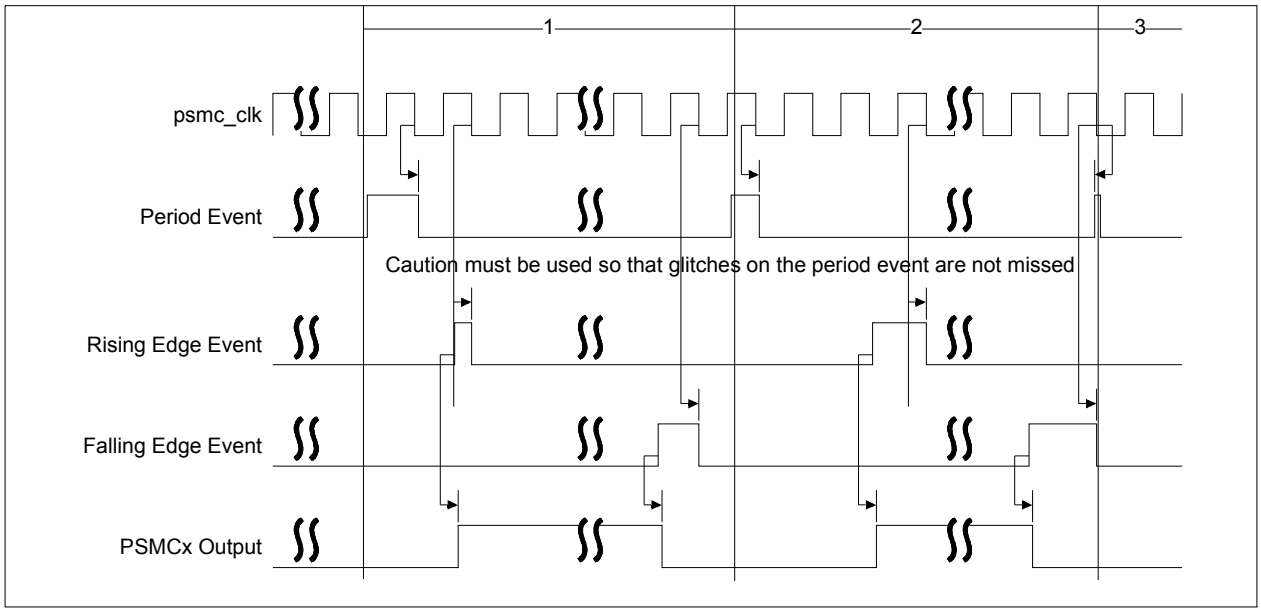
Synchronization is achieved by sending a sync signal from the master PSMC module to the desired slave modules. This sync signal generates a period event in each slave module, thereby aligning all slaves with the master. This is useful when an application requires different PWM signal generation from each module but the waveforms must be consistent within a PWM period.

26.8.1 SYNCHRONIZATION SOURCES

The synchronization source can be any PSMC module on the same device. For example, in a device with two PSMC modules, the possible sources for each device is as shown below:

- Sources for PSMC1
  - PSMC2
- Sources for PSMC2
  - PSMC1

FIGURE 26-21: PSMC SYNCHRONIZATION - SYNC OUTPUT TO PIN



26.8.1.1 PSMC Internal Connections

The sync signal from the master PSMC module is essentially that modules period event trigger. The slave PSMC modules reset their PSMCxTMR with the sync signal instead of their own period event.

Enabling a module as a slave recipient is done with the PxSYNC bits of the PSMC Synchronization Control (PSMCxSYNC) registers; registers 26-3 and 26-4.

26.8.1.2 Phase Offset Synchronization

The synchronization output signal from the PSMC module is selectable. The sync_out source may be either:

- Period Event
- Rising Event

Source selection is made with the PxPOFST bit of the PSMCxSYNC registers, registers 26-3, 26-4 and 26-7.

When the PxPOFST bit is set, the sync_out signal comes from the rising event and the period event replaces the rising event as the start of the active drive period. When PxPOFST is set, duty cycles of up to 100% are achievable in both the slave and master.

When PXPOFST is clear, the sync_out signal comes from the period event. When PxPOFST is clear, rising events that start after the period event remove the equivalent start delay percentage from the maximum 100% duty cycle.

26.8.1.3 Synchronization Skid

When the sync_out source is the Period Event, the slave synchronous rising and falling events will lag by one psmc_clk period. When the sync_out source is the Rising Event, the synchronous events will lag by two clock periods. To compensate for this, the values in PHH:PHL and DCH:DCL registers can be reduced by the number of lag cycles.

26.12 Register Definitions: PSMC Control

REGISTER 26-1: PSMCxCON: PSMC CONTROL REGISTER

R/W-0/0	R/W/HC-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
PSMCxEN	PSMCxLD	PxDBFE	PxDBRE	PxMODE<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **PSMCxEN:** PSMC Module Enable bit
- 1 = PSMCx module is enabled
- 0 = PSMCx module is disabled

bit 6 **PSMCxLD:** PSMC Load Buffer Enable bit
- 1 = PSMCx registers are ready to be updated with the appropriate register contents
- 0 = PSMCx buffer update complete

bit 5 **PxDBFE:** PSMC Falling Edge Dead-Band Enable bit
- 1 = PSMCx falling edge dead band enabled
- 0 = PSMCx falling edge dead band disabled

bit 4 **PxDBRE:** PSMC Rising Edge Dead-Band Enable bit
- 1 = PSMCx rising edge dead band enabled
- 0 = PSMCx rising edge dead band disabled

bit 3-0 **PxMODE<3:0>** PSMC Operating Mode bits
- 1111 = Reserved
- 1110 = Reserved
- 1101 = Reserved
- 1100 = 3-phase steering PWM
- 1011 = Fixed duty cycle, variable frequency, complementary PWM
- 1010 = Fixed duty cycle, variable frequency, single PWM
- 1001 = ECCP compatible Full-Bridge forward output
- 1000 = ECCP compatible Full-Bridge reverse output
- 0111 = Pulse-skipping with complementary output
- 0110 = Pulse-skipping PWM output
- 0101 = Push-pull with four full-bridge outputs and complementary outputs
- 0100 = Push-pull with four full-bridge outputs
- 0011 = Push-pull with complementary outputs
- 0010 = Push-pull output
- 0001 = Single PWM with complementary output (with PWM steering capability)
- 0000 = Single PWM waveform generation (with PWM steering capability)

FIGURE 27-19: I²C SLAVE, 7-BIT ADDRESS, TRANSMISSION (AHEN = 1)

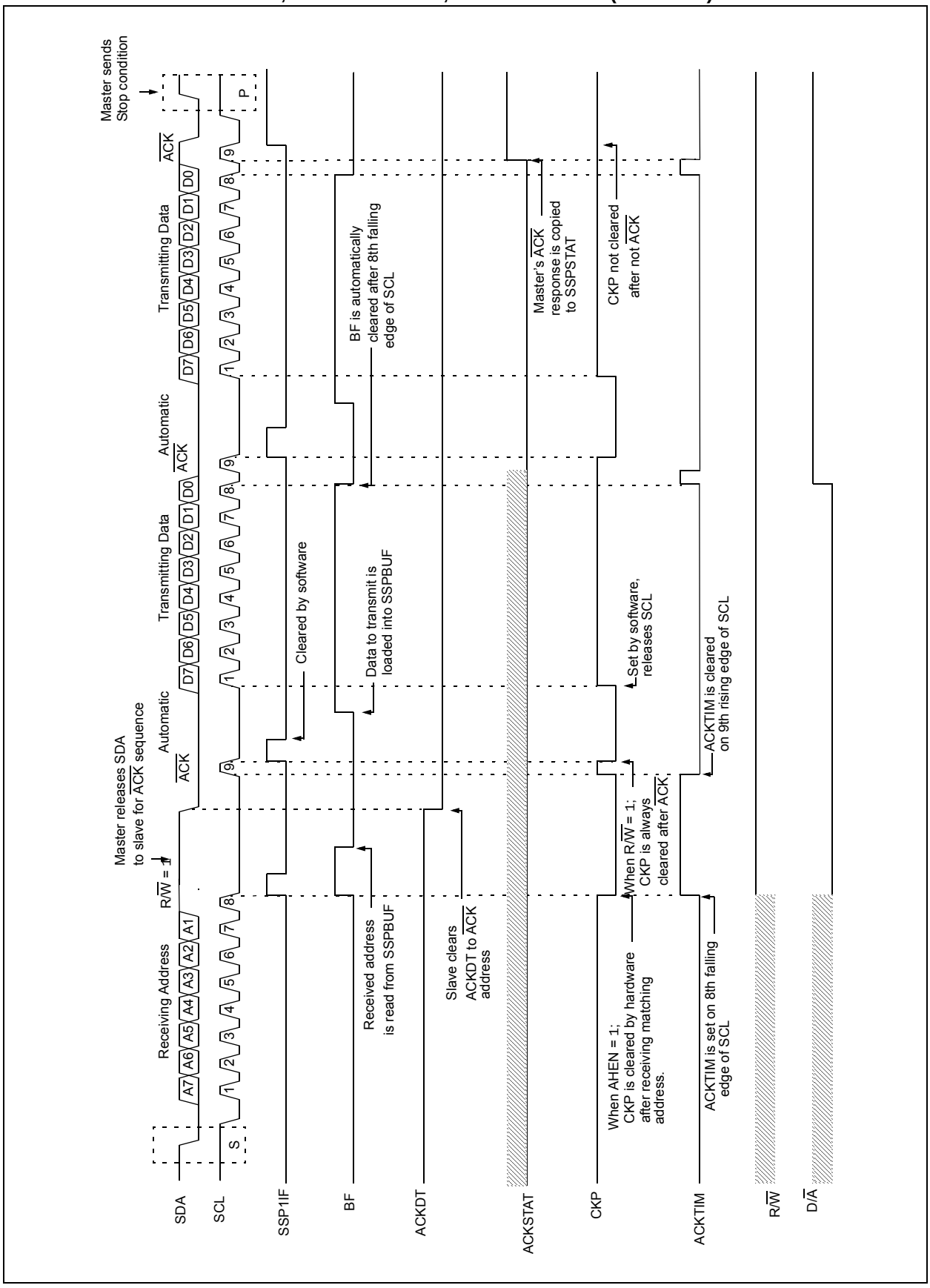
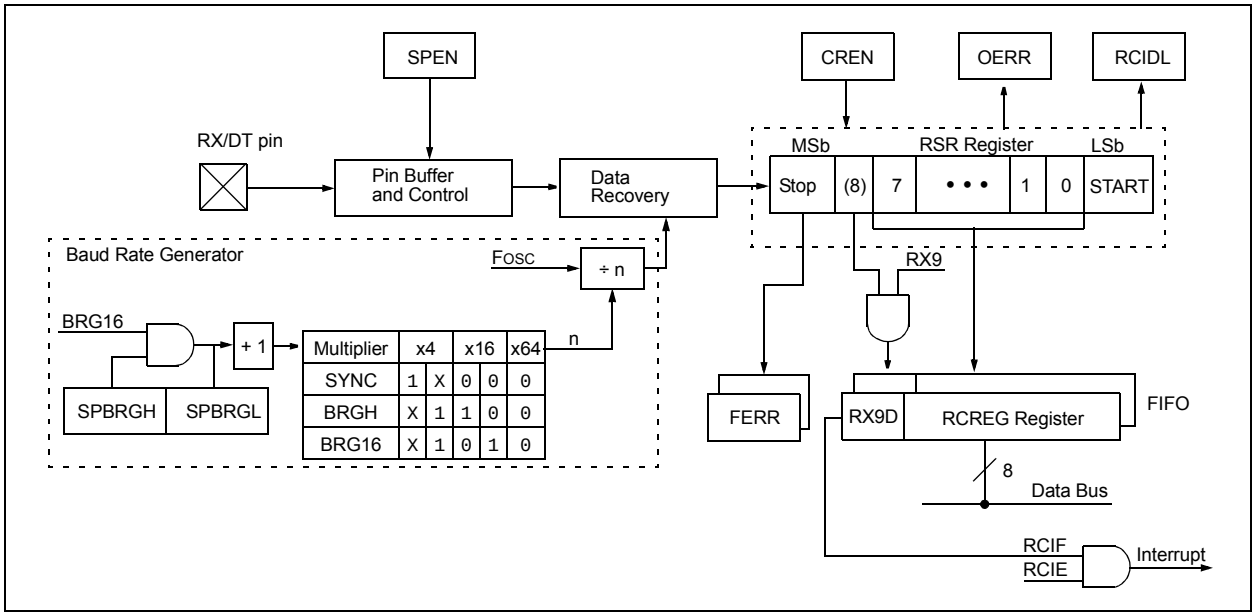


FIGURE 28-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 28-1, Register 28-2 and Register 28-3, respectively.

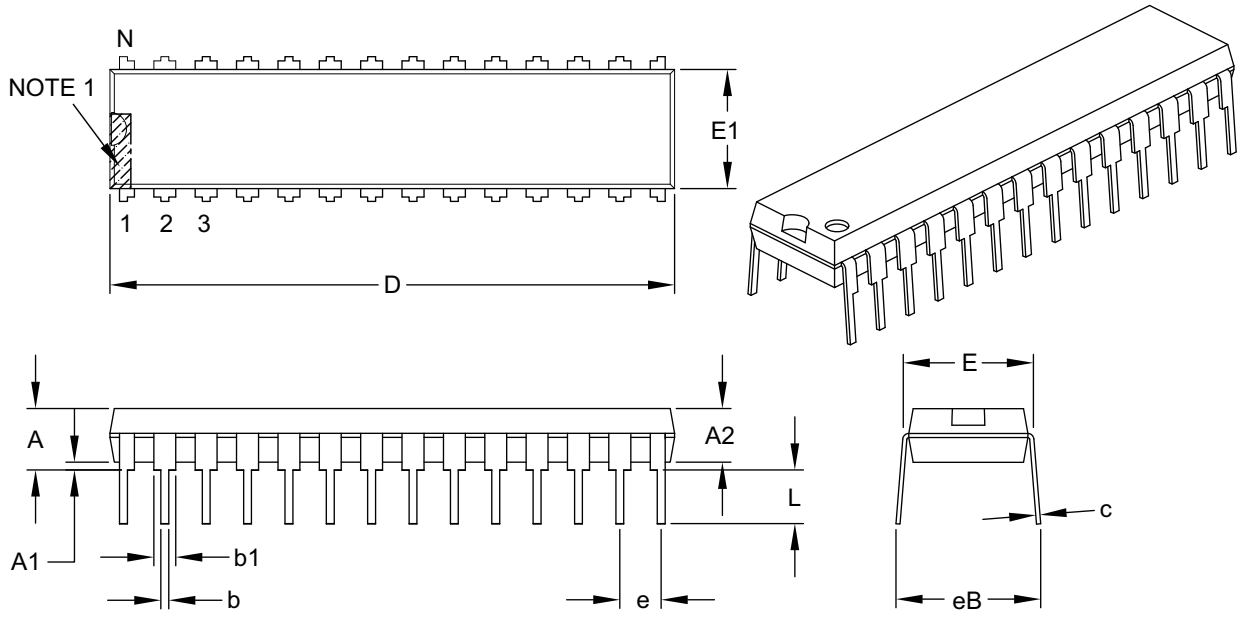
When the receiver or transmitter section is not enabled then the corresponding RX or TX pin may be used for general purpose input and output.

34.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

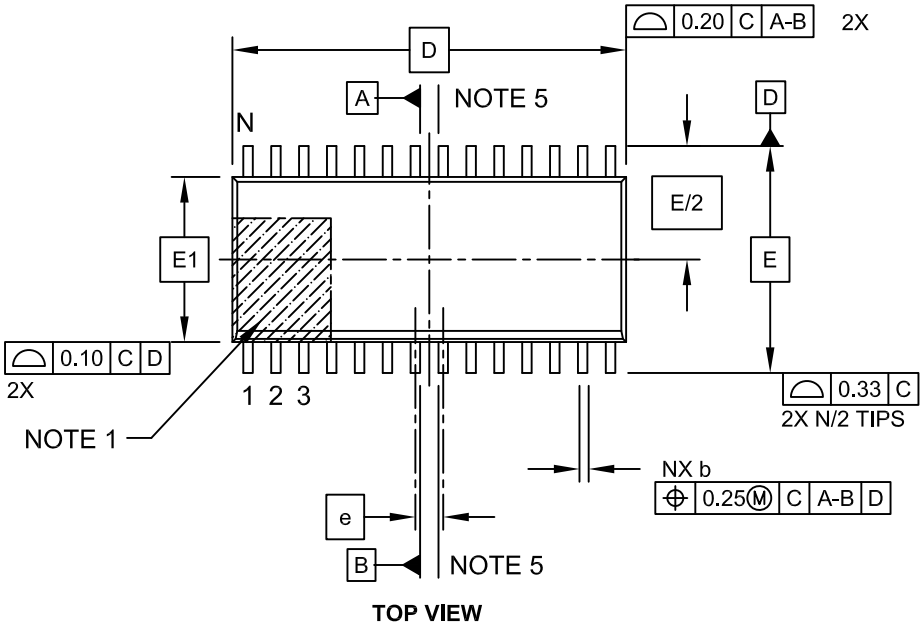
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

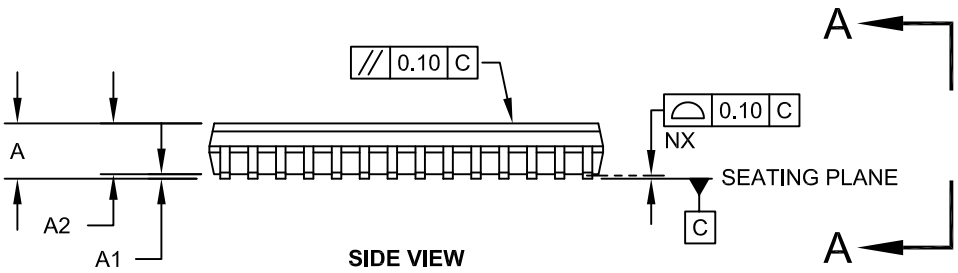
Microchip Technology Drawing C04-070B

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

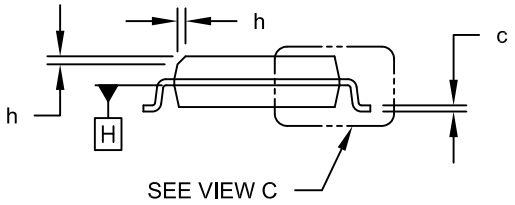
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

Microchip Technology Drawing C04-052C Sheet 1 of 2

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